



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20130903001
Add Cu as Alternative Wire Base Metal for Selected Device(s)
Change Notification / Sample Request

Date: 9/6/2013
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

20130903001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TMP75AID	null
TMP75AIDG4	null
TMP75AIDR	null
TMP75AIDRG4	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20130903001			PCN Date:	09/06/2013
Title:	Add Cu as Alternative Wire Base Metal for Selected Device(s)				
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037		Dept:
Proposed 1st Ship Date:	12/06/2013		Estimated Sample Availability:	Date provided at sample request	
Change Type:					
<input type="checkbox"/> Assembly Site	<input checked="" type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Assembly Materials			
<input type="checkbox"/> Design	<input type="checkbox"/> Electrical Specification	<input type="checkbox"/> Mechanical Specification			
<input type="checkbox"/> Test Site	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process			
<input type="checkbox"/> Wafer Bump Site	<input type="checkbox"/> Wafer Bump Material	<input type="checkbox"/> Wafer Bump Process			
<input type="checkbox"/> Wafer Fab Site	<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Wafer Fab Process			
	<input type="checkbox"/> Part number change				
PCN Details					
Description of Change:					
<p>Texas Instruments is pleased to announce the qualification of Cu as an additional bond wire option for devices listed in "Product affected" section below. Devices will remain in current assembly facility and assembly differences are as follows:</p>					
Group 1 Device:					
	Current Assembly	Bond wire option			
Wire type	Au wire	Cu wire			
Group 2 Device:					
	Current Assembly	Alternate Assembly			
Wire type	Au	Cu			
Leadframe thickness	8mils	6mils			
Mold compound	4205694	4211880			
Reason for Change:					
<p>Continuity of supply.</p> <ol style="list-style-type: none"> 1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties 2) Maximize flexibility within our Assembly/Test production sites. 3) Cu is easier to obtain and stock 					

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
None.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected: Group 1			
TPS65149RSHR			
Product Affected: Group 2			
TMP75AID	TMP75AIDG4	TMP75AIDR	TMP75AIDRG4

Qualification Data : Group 1					
This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.					
Qual Vehicle 1: TPS65149RSH (MSL 3-260C)					
Package Construction Details					
Assembly Site:	CRS	Mold Compound:	435370		
# Pins-Designator, Family:	56-RSH, QFN	Mount Compound:	435143		
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	1.3Mil Cu		
Qualification:	<input type="checkbox"/> Plan	<input checked="" type="checkbox"/> Test Results			
Reliability Test	Conditions		Sample Size/Fail		
			Lot #1	Lot #2	Lot #3
Electrical Characterization	-		Pass	-	-
**Autoclave	121C, 2atm (168hrs)		82/0	82/0	82/0
**T/C -65C/150C	-65C/+150C (500 Cyc)		82/0	81/0	82/0
**High Temp. Storage Bake	150C (1000 hrs)		82/0	82/0	82/0
Manufacturability	(per mfg. Site specification)		Pass	Pass	Pass
Notes **- Preconditioning sequence: Level 3-260C.					

Qualification Data : Group 2

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle 1: OPA-2364ID (MSL 2-260C)

Package Construction Details

Assembly Site:	MLA	Mold Compound:	4211880
# Pins-Designator, Family:	8-D, SOIC	Mount Compound:	4042500
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96Mil Cu

Qualification: **Plan** **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot #1	Lot #2	Lot #3
**Autoclave	121C, 2atm (96hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
**High Temp. Storage Bake	170C (420 hrs)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass

Notes **- Preconditioning sequence: Level 2-260C.

Qual Vehicle 2: SN0910049DR (MSL 2-260C)

Package Construction Details

Assembly Site:	MLA	Mold Compound:	4211880
# Pins-Designator, Family:	16-D, SOIC	Mount Compound:	4042500
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96Mil Cu

Qualification: **Plan** **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot #1	Lot #2	Lot #3
**Autoclave	121C, 2atm (96hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	77/0	77/0	77/0
**High Temp. Storage Bake	170C (420 hrs)	77/0	77/0	77/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass

Notes **- Preconditioning sequence: Level 2-260C.

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com